

Hirata

Security code : 6258
February 2026

Financial Results Explanatory Materials

FY2025 (March 2026)
Third quarter

Note : This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

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※FY2025 represents the fiscal year ending March 31, 2026.

Company Profile

Company Name	HIRATA Corporation
Address	111 Hitotsugi, Ueki, Kita, Kumamoto, 861-0198 Japan
Representatives	Yuichiro Hirata, President
Date Established	December 29, 1951
Capital	2,633 million yen
Our business	Manufacture and sales of various manufacturing systems, industrial robots and logistic equipment, etc.
Stock Exchange Listings	Tokyo Stock Exchange, Prime Market (Security Code : 6258)
Employees	Consolidated 2,371 Non-Consolidated 1,574 ※As of December 31, 2025
Plants and office	7 bases in Japan(4 bases in Kumamoto 1 each in Tochigi, Shiga, Tokyo)
Subsidiaries	3 subsidiaries in Japan(2 in Kumamoto, 1 in Tokyo) 9 overseas subsidiaries(America, Mexico, Singapore, Malaysia, 2 in China, Taiwan, Thailand※, Germany※)

※ We are currently in the process of liquidating our affiliated companies in Thailand and Germany.

I . FY2025 Third Quarter Results (Consolidated)

Financial Summary

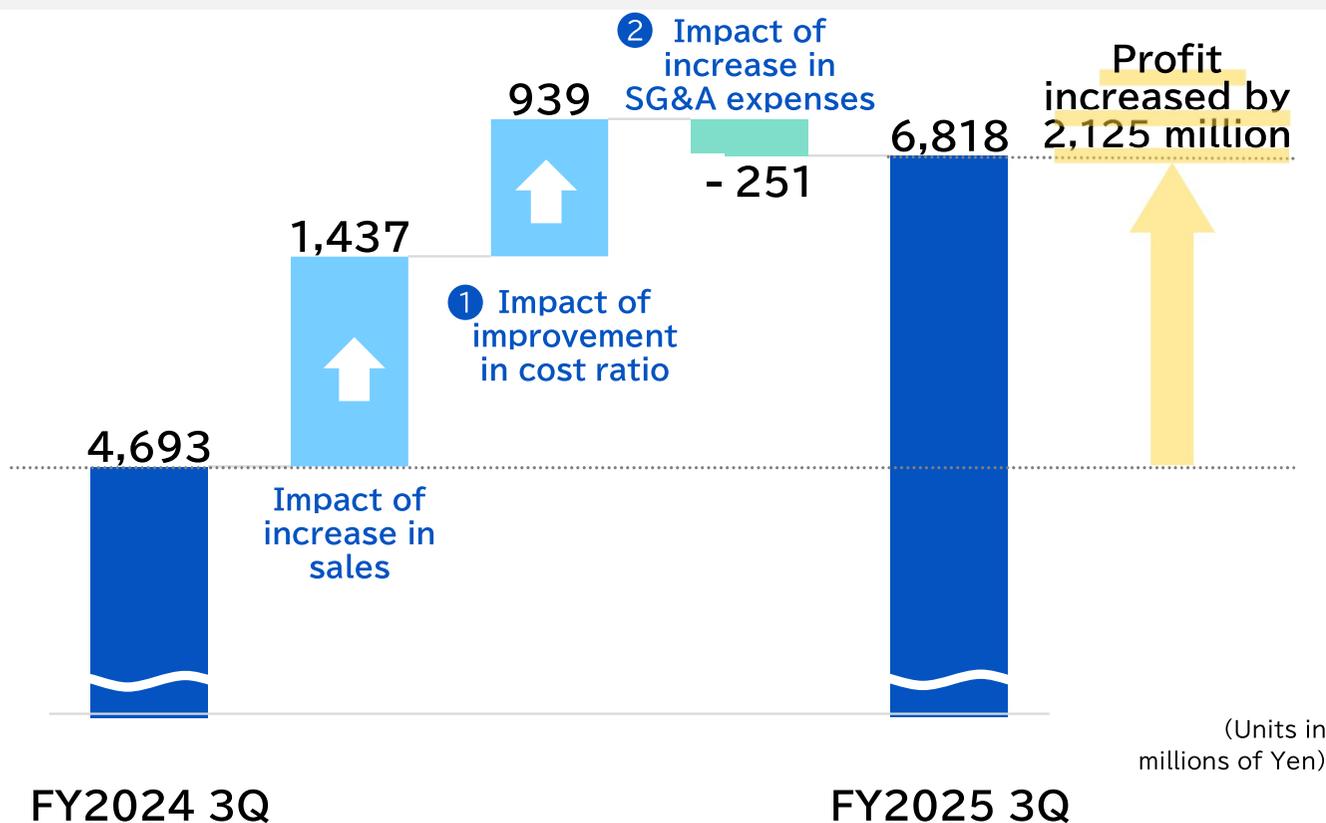
- **Received orders** Received orders increased compared to the same period last year, driven by orders of large project in the automobile-related business and strong generative-AI related demand in the semiconductor-related business.
- **Sales** Sales increased compared to the same period last year, driven by higher order volumes, production advanced in both the automobile- and semiconductor-related business.
- **Operating profit** Operating profit increased compared to the same period last year, supported by higher sales and improved cost ratios in the automobile-related business and other automatic labor-saving equipment.

(Units in millions of Yen)

	FY2024 3Q	FY2025 3Q	YoY Change	
	Actual results	Actual results	Amount of +/-	Percentage of +/-
Received orders	58,958	71,961	13,002	22.1%
Net Sales	62,323	69,118	6,795	10.9%
Backlog of Orders	62,040	59,276	-2,763	-4.5%
Operating Profit (Operating profit ratio)	4,693 7.5%	6,818 9.9%	2,125	45.3%
Ordinary Profit	4,502	6,927	2,425	53.9%
Net income attributable to owners of the parent for the interim period	2,939	4,703	1,764	60.0%

Factor Analysis on Changing Operating Profit

- Operating profit increased 2,125 million yen from the same period of the previous year.
 - **Main factors for increase** : Increase in sales, improvement in cost ratio



1 Impact of improvement in cost ratio
 Cost ratio 78.8% ⇒ 77.5%

Main factors contributing to the improvement in cost ratio

- Promotion of price pass-through (mainly in automobile-related business)
- Improved profitability through enhanced proficiency (mainly in automobile-related business)

2 Impact of increase in SG&A expenses

- Increase in labor costs driven by pay raises and growth in staff members, etc.

I. FY2025 Third Quarter Results (Consolidated)

Results by Segment

* Elimination of intersegment transactions is included in 'Others'.

(Units in millions of Yen)		FY2024 3Q	FY2025 3Q	Amount of +/-	Percentage of +/-
Received orders	Total	58,958	71,961	13,002	22.1%
	Automobile	27,863	38,419	10,555	37.9%
	Semiconductor	21,695	23,347	1,651	7.6%
	Other Automatic Labor-saving Equipment	7,741	8,565	824	10.6%
	Others	1,658	1,629	-28	-1.7%
Net Sales	Total	62,323	69,118	6,795	10.9%
	Automobile	30,061	33,525	3,463	11.5%
	Semiconductor	21,409	24,468	3,058	14.3%
	Other Automatic Labor-saving Equipment	9,319	9,520	200	2.2%
	Others	1,531	1,604	72	4.7%
Backlog of orders	Total	62,040	59,276	-2,763	-4.5%
	Automobile	36,952	35,096	-1,856	-5.0%
	Semiconductor	19,756	17,892	-1,863	-9.4%
	Other Automatic Labor-saving Equipment	4,716	5,595	878	18.6%
	Others	614	692	77	12.5%
Operating profit	Total	4,693	6,818	2,125	45.3%
	Automobile	2,688	4,468	1,779	66.2%
	Semiconductor	2,544	1,693	-850	-33.4%
	Other Automatic Labor-saving Equipment	-525	599	1,124	-
	Others	-14	57	71	-

Results by Segment : Automobile-related business

- Received orders** Received orders increased compared to the same period last year, driven by strong order demands of internal combustion engines(ICE) for North America and hybrid-related business.
- Sales** Sales increased compared to the same period last year, as internal combustion engine-related business increased although EV-related business, mainly in EDU decreased.
- Operating profit** Operating profit increased compared to the same period last year, as profitability improved due to appropriate price setting and enhanced proficiency.

(Units in millions of Yen)

	FY2024 3Q		FY2025 3Q		YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Received orders	27,863	-	38,419	-	10,555	37.9%
EV (incl HV)	19,814	71.1%	15,714	40.9%	-4,099	-20.7%
ICE, etc.	8,049	28.9%	22,704	59.1%	14,655	182.1%
Net Sales	30,061	-	33,525	-	3,463	11.5%
EV (incl HV)	19,774	65.8%	18,157	54.2%	-1,617	-8.2%
ICE, etc.	10,286	34.2%	15,368	45.8%	5,081	49.4%
Backlog of orders	36,952	-	35,096	-	-1,856	-5.0%
Operating profit	2,688	-	4,468	-	1,779	66.2%
Operating profit ratio	8.9%	-	13.3%	-	-	-

Results by Segment : Semiconductor-related business

- Received orders** Received orders increased compared to the same period last year, supported by continued demand for generative-AI related products, especially for foundry.
- Sales** Sales increased compared to the same period last year, as production progressed mainly in wafer transfer systems and packaging-related business as well.
- Operating profit** Operating profit decreased compared to the same period last year, due to a worsening cost ratio resulting from rising material costs and delays in price pass-through. However, from 2Q onward, efforts to improve costs and implement price pass-through progress.

(Units in millions of Yen)

	FY2024 3Q		FY2025 3Q		YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Received orders	21,695	-	23,347	-	1,651	7.6%
Wafer transfer	17,672	81.5%	16,681	71.4%	-991	-5.6%
Others	4,022	18.5%	6,665	28.6%	2,642	65.7%
Net Sales	21,409	-	24,468	-	3,058	14.3%
Wafer transfer	15,002	70.1%	17,442	71.3%	2,440	16.3%
Others	6,407	29.9%	7,025	28.7%	618	9.7%
Backlog of orders	19,756	-	17,892	-	-1,863	-9.4%
Operating profit	2,544	-	1,693	-	-850	-33.4%
Operating profit ratio	11.9%	-	6.9%	-	-	-

Results by Segment : Other Automatic Labor-saving Equipment

- Received orders** Received orders increased compared to the same period last year, driven by demand for organic EL-related business.
- Sales** Sales remained on par with the same period last year, although sales in home appliances-related business declined, organic EL-related sales increased.
- Operating profit** Operating profit increased compared to the same period last year, supported by higher sales of organic EL-related business with high proficiency, along with the elimination of unprofitable projects.

(Units in millions of Yen)

	FY2024 3Q		FY2025 3Q		YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Received orders	7,741	-	8,565	-	824	10.6%
Net Sales	9,319	-	9,520	-	200	2.2%
Backlog of orders	4,716	-	5,595	-	878	18.6%
Operating profit	-525	-	599	-	1,124	-
Operating profit ratio	-5.6%	-	6.3%	-	-	-

Balance Sheet

(Units in millions of Yen)

Assets	FY2024	FY2025 3Q	+/-	Liabilities	FY2024	FY2025 3Q	+/-
Current Assets	88,035	99,238	11,203	Current liabilities	43,295	53,806	10,511
Cash & deposits	12,882	27,252	14,369	Trade payables	10,574	10,224	-350
Accounts receivables	56,561	49,939	-6,622	Short-term borrowings*	22,330	27,122	4,792
Inventories	15,510	19,193	3,682	Others	10,390	16,459	6,069
Others	3,080	2,853	-227	Fixed liabilities	18,143	18,024	-119
Non-Current Assets	42,243	45,068	2,825	Long-term borrowings	11,836	11,534	-301
Tangible fixed assets	26,592	27,857	1,264	Others	6,307	6,489	181
Intangible fixed assets	1,160	1,163	2	Total Liabilities	61,439	71,831	10,391
Investment & other assets	14,489	16,048	1,558	Total Net Assets	68,839	72,476	3,636
Total Assets	130,278	144,307	14,028	Total Liabilities and Net Assets	130,278	144,307	14,028

Main factors for increase/decrease

- Cash & deposits increased as a result of customer payments.
- Accounts receivables decreased as a result of customer payments. Payment collection terms are also trending toward improvement.
- Other current liabilities increased as contract liabilities rose due to advanced payments received from customers.

* including long-term borrowings due within one year

II. FY2025 Full Year Forecasts (Consolidated)

Full Year Forecast

- We anticipate an increase in revenue to 96 billion yen and an increase in operating profit to 8.4 billion yen for the fiscal year 2025 (ending March 2026).

Unchanged from the May 2025 announcement.

(Units in millions of Yen)

	FY2024	FY2025	YoY Change	
	Results	Full year forecast	Amount of +/-	Percentage of +/-
Net Sales	88,483	96,000	7,516	8.5%
Automobile-related business	43,059	*43,000	-59	-0.1%
Semiconductor-related business	30,186	*36,000	5,813	19.3%
Other Automatic Labor-saving Equipment	13,096	*15,000	1,903	14.5%
Others	2,141	*2,000	-141	-6.6%
Operating Profit (x)	6,898 (7.8%)	8,400 (8.8%)	1,501	21.8%
Ordinary Profit (x)	6,889 (7.8%)	8,200 (8.5%)	1,310	19.0%
Profit attributable to owners of parent (x)	4,778 (5.4%)	5,700 (5.9%)	921	19.3%

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Transition and Forecast of Dividends and Dividend Ratio per Share

(Units in Yen)

	FY2020	FY2021	FY2022	FY2023	FY2024	FY2025 forecast
Dividends per Share*	21.7	21.7	30.0	33.3	40.0	65.0
Consolidated dividend payout ratio(%)	16.6	25.2	21.9	23.9	25.9	35.3

Amount of treasury shares acquired : approx. 1 billion yen
Total shareholder return ratio : **46.7%**

<Our approach to dividends>

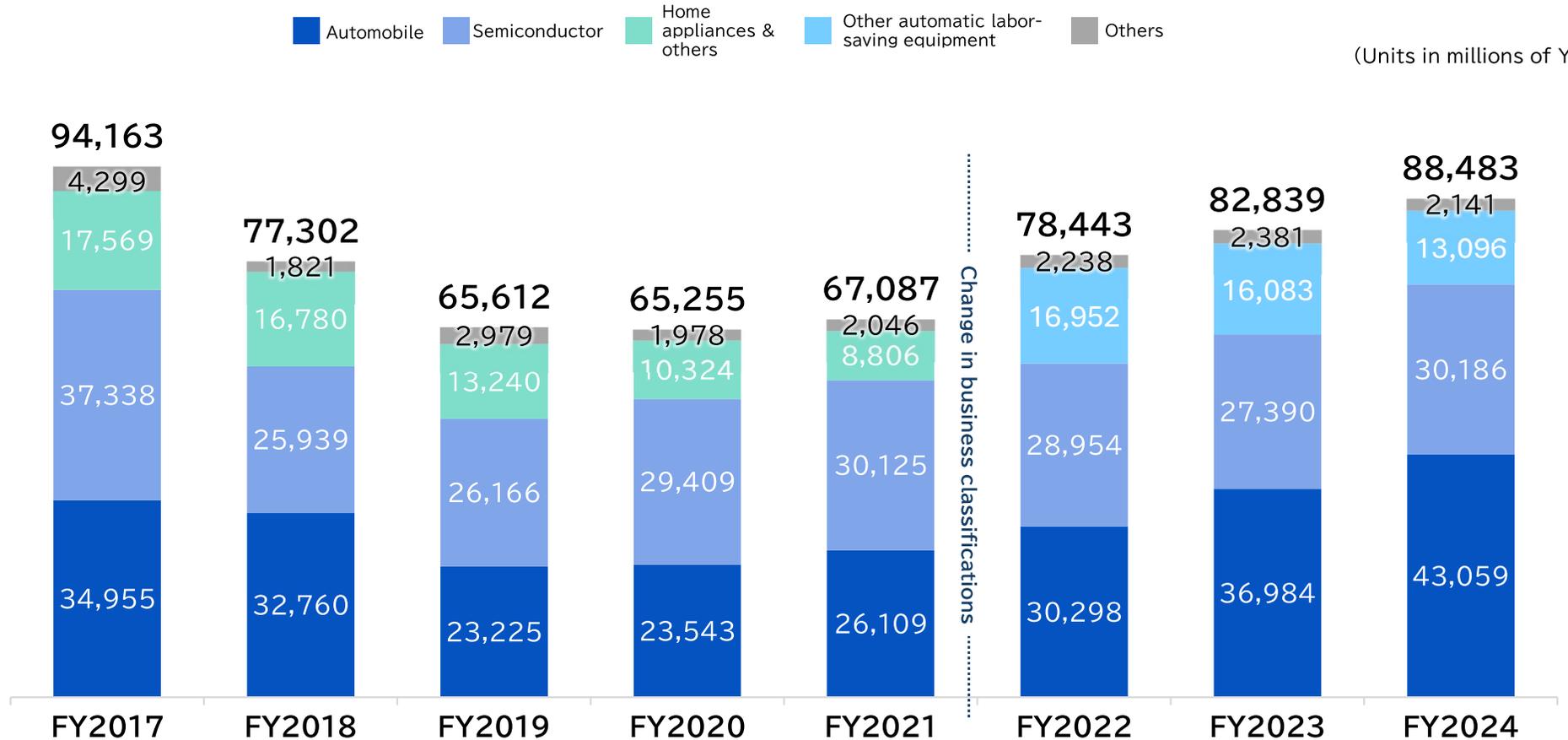
For dividends from the fiscal year 2025 onwards, based on the growth strategy aimed at enhancing corporate value as outlined in the medium-term management plan (FY2025-2027), we have established the allocation of growth investments and shareholder returns within our cash allocation policy, and decided to raise the target consolidated dividend payout ratio to a level from 20% to 35%.

For the fiscal year 2025's dividend, we anticipate a year-end dividend of 65 yen.

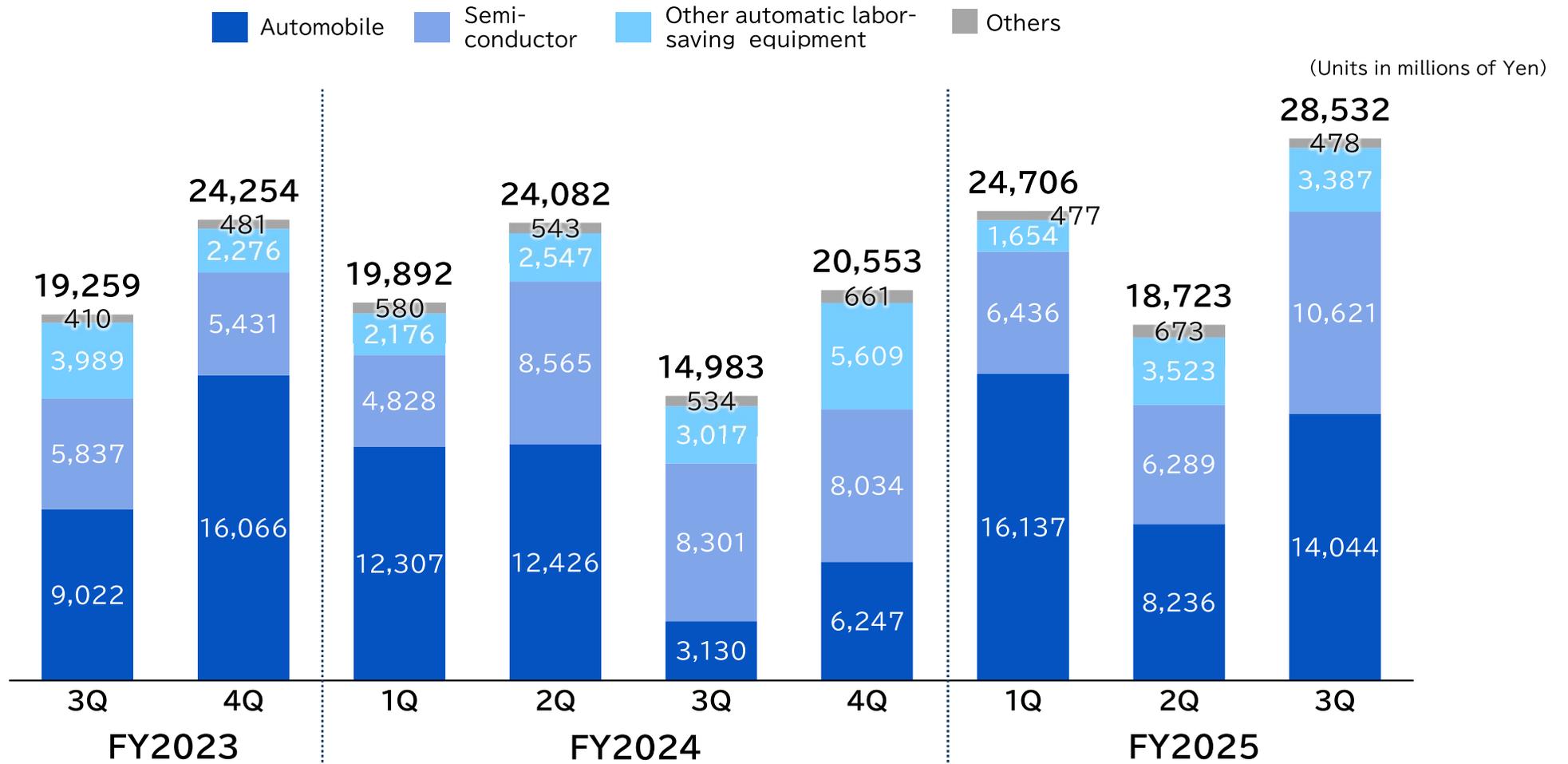
*The dividends per share reflects the impact of the share split (three-for-one), which became effective on April 1, 2025.

III. Reference Data

Net Sales by Business Segment (FY2017 to FY 2024)



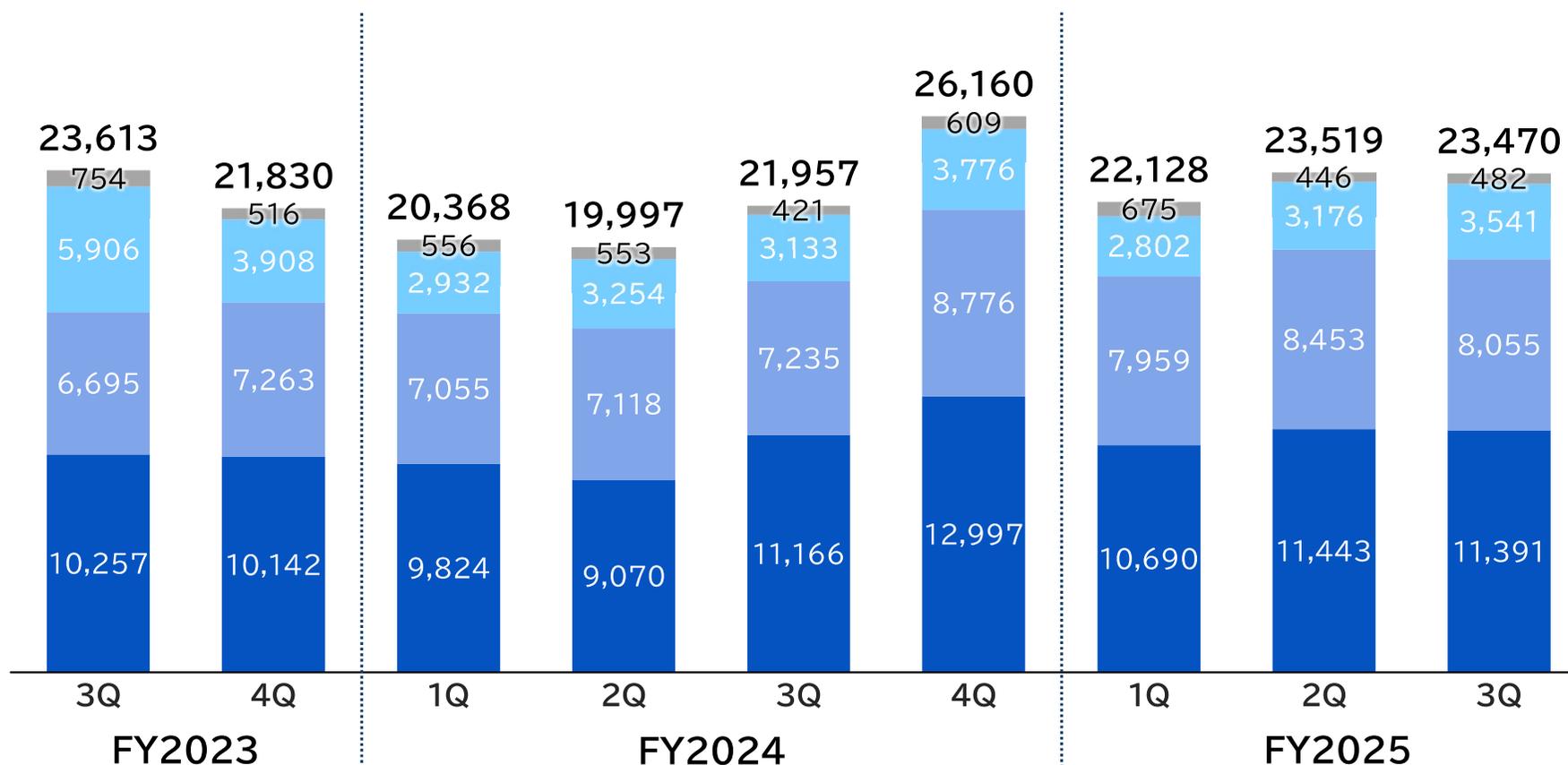
Received Orders by Business Segment (Quarterly)



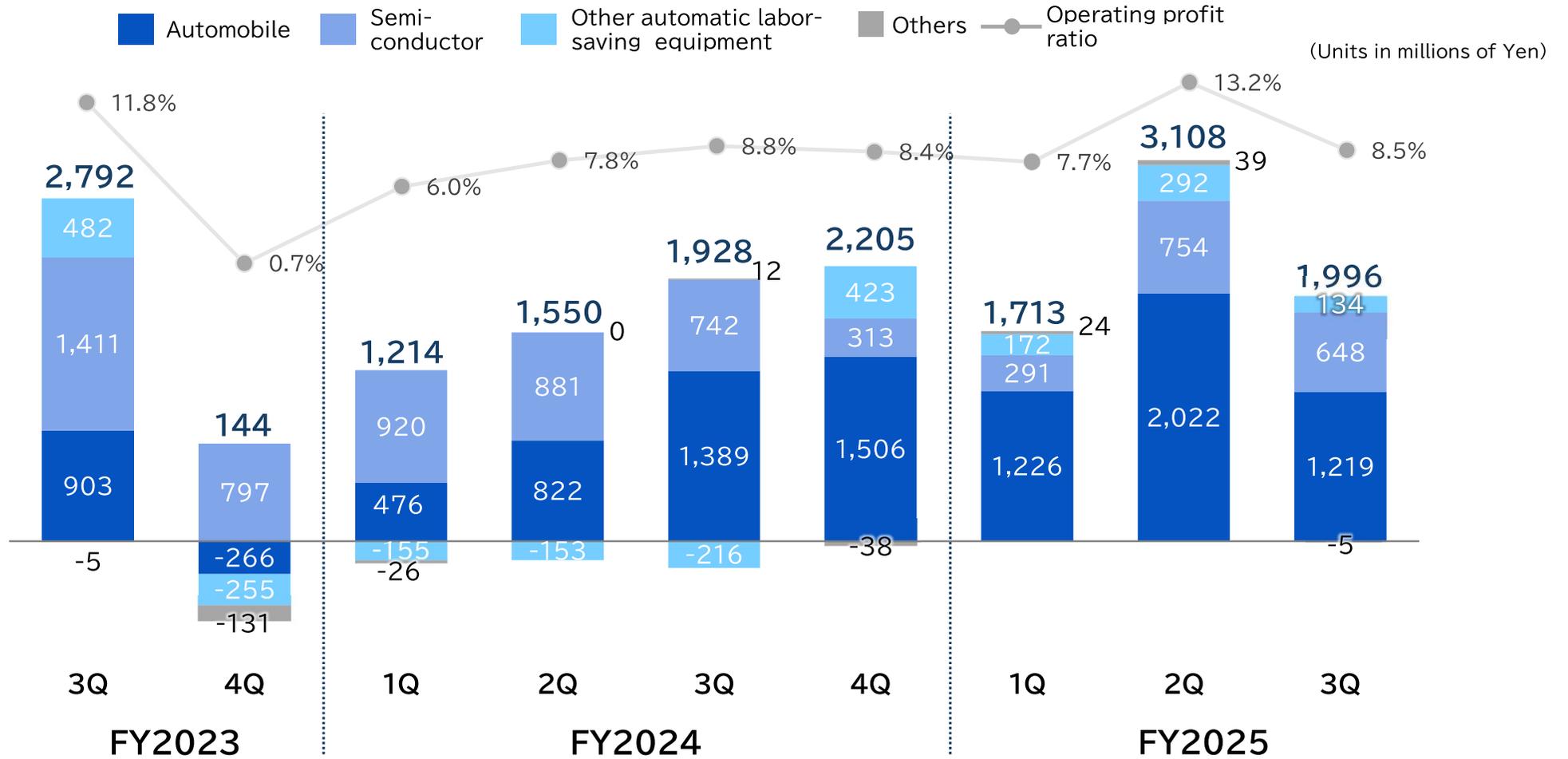
Net Sales by Business Segment (Quarterly)



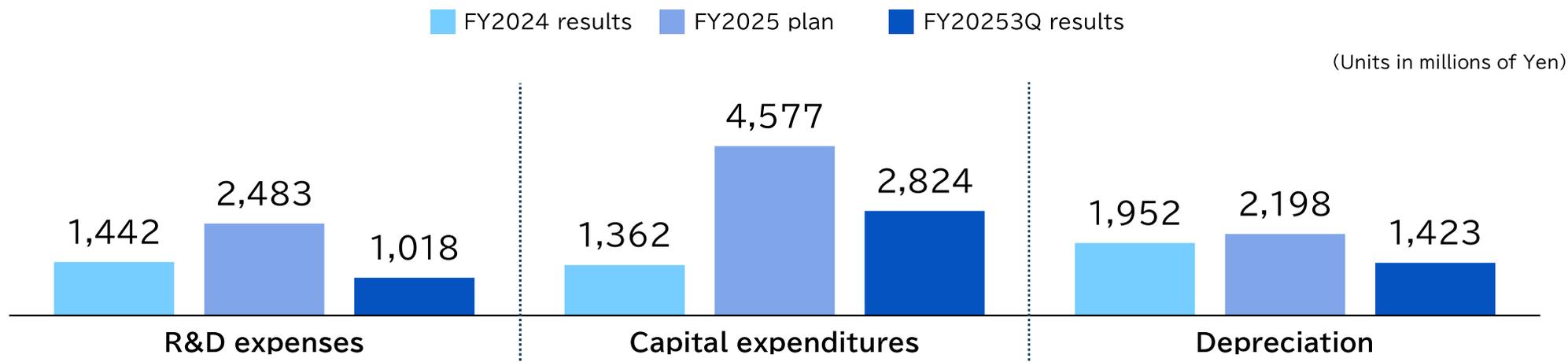
(Units in millions of Yen)



Operating Profit by Business Segment (Quarterly)



R&D expenses, CAPEX, and Depreciation expenses



R&D expenses ***1,018 million yen**

- Development of mass-produced products and next generation products

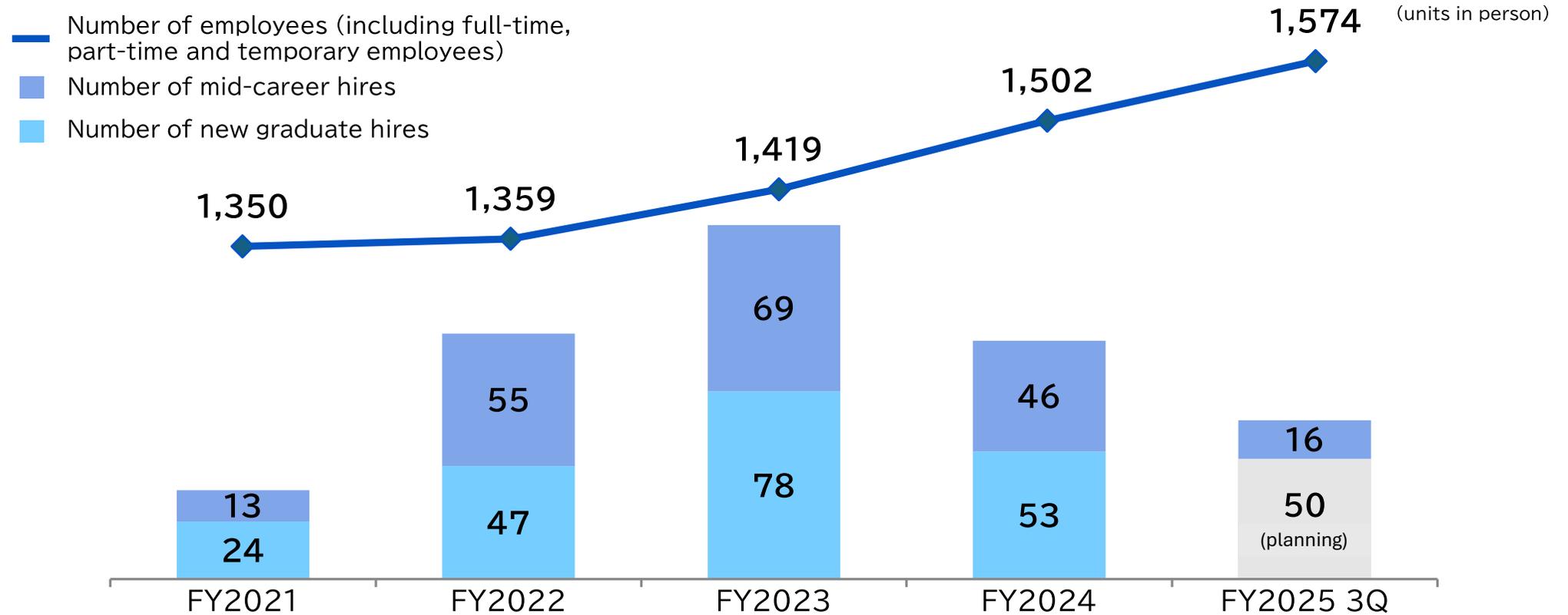
Capital expenditures **2,824 million yen**

- Acquired the Shichijo No.2 plant (land and buildings) primarily as a production site for control panels
- Conducted additional capital investments to expand production capacity

* Although costs arise for technology development and improvements in the course of our business activities, those directly attributable to individual projects are recorded as cost of sales and are not included in R&D expenses.

Number of Recruits · Employees (Non-consolidated · End of period)

- In anticipation of business expansion, we are committed to ensuring a continuous supply of talented professionals.
- We are working on talent retention through various measures such as wage improvements, workstyle reforms, enhancing employee benefits, and providing quality education and training opportunities.



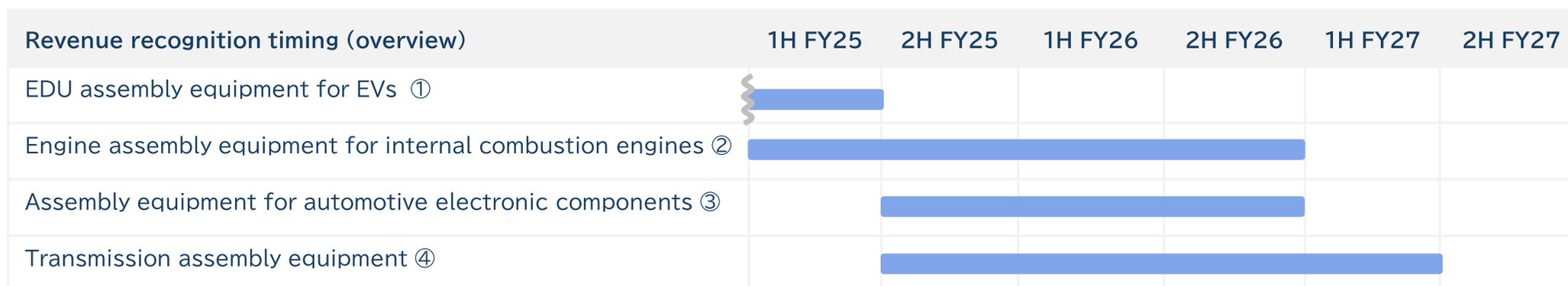
External Environment Assessment

Segment	Hirata's external environment assessment	
<p>Automobile-related business</p> 		<ul style="list-style-type: none"> • Capital investments in the United States are expanding in response to U.S. tariff measures. • Capital investments related to internal-combustion and hybrid systems are on an upward trend.
<p>Semiconductor-related business</p> 		<ul style="list-style-type: none"> • Capital investments are expanding especially for generative-AI related business. • Technological innovation in packaging process is driving stronger demand for clean-transport systems.
<p>Other automatic-labor saving equipment</p> 		<ul style="list-style-type: none"> • Demand for automation and labor-saving solutions is increasing across various industries and sectors, including logistics and healthcare.
		<ul style="list-style-type: none"> • Capital investments by existing customers have declined.

Disclosed information : Receipt of Large Project Orders

- We continue to receive large-scale equipment orders and recognize revenue in line with construction progress.

Disclosure date		Outline of the equipment	Order amount
FY2024	May	Battery charging and discharging related equipment for EVs	Approximately 2.5 billion yen
	August	Battery charging and discharging related equipment for EVs	Approximately 5.6 billion yen
	August	EDU assembly equipment for EVs ①	Approximately 8.7 billion yen
FY2025	May	Engine assembly equipment for internal combustion engines ②	Approximately 10 billion yen
	September	Assembly equipment for automotive electronic components ③	More than 6 billion yen
	December	Transmission assembly equipment ④	Approximately 8 billion yen



Strengthening our Efforts in ESG Management

2023	Apr.	The Sustainability Promotion Committee is established.	 <p>WE SUPPORT UN GLOBAL COMPACT</p>
		Sustainability page is established in our web page and the dissemination of ESG information is been strengthened.	
	Sep.	We sign the UN Global Compact.	
	Oct.	Human rights due diligence is implemented.	
	Nov.	We express our support for the Keidanren’s ”Charter of Corporate Behavior.”	
2024	Jan.	Code of Conduct of the Hirata Group is established.	 <p>FTSE Blossom Japan Index</p>  <p>FTSE Blossom Japan Sector Relative Index</p>
		Human Rights Respect Working Group within the Sustainability Promotion Committee is established.	
	Jun.	We selected as a constituent stock for: 「FTSE Blossom Japan Index」 「FTSE Blossom Japan Sector Relative Index」	
	Nov.	We endorse the Keidanren Declaration for Biodiversity and Guideline.	
2025	Mar.	We obtain the ”Silver” rating in the EcoVadis sustainability assessment.	 <p>SILVER Top 15% ecovadis Sustainability Rating FEB 2025</p>

Business Overview : Main Products of Automobile-related Business

- We manufacture and supply various production equipment to North American automakers (Big three), North American emerging EV manufacturers, domestic electronic components manufacturers, and so on.

Main/Expansion fields of automobile-related business

<p>Main field</p> <h3>Engine assembly equipment</h3> <p>Equipment for assembling gasoline, diesel, and other internal combustion engines. Due to the extremely large number of parts involved, some assembly lines can exceed a total length of 1 kilometer.</p>  <p>Equipment we design and manufacture → Finished products</p> <p>Main customers</p> <ul style="list-style-type: none"> • North American automakers (Big three) 	<p>Main field</p> <h3>EDU assembly equipment</h3> <p>Assembly equipment for Electric Drive Units (EDU) – drive components for EVs that combine an onboard motor with a gearbox.</p>  <p>Equipment we design and manufacture → Finished products</p> <p>Main customers</p> <ul style="list-style-type: none"> • North American automakers (Big three) • North American emerging EV manufacturers 	<p>Main field</p> <h3>IGBT·Inverter assembly equipment</h3> <p>Assembly equipment for automotive electronic components such as IGBTs and inverters, which are installed in EVs and vehicles with automatic transmissions.</p>  <p>Equipment we design and manufacture → Finished products</p> <p>Main customers</p> <ul style="list-style-type: none"> • Domestic electronic components manufacturers
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Hirata's competitive advantages

- Broad capability to deliver a wide range of products for both EVs and internal combustion engines.
- Technical capabilities to handle large facilities, some of which exceed 1 km in total length, solely in-house.
- Engineering capabilities enable an integrated process—from development through production to maintenance—that consistently meets diverse customer requirements.

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BEV HV·PHV ICE FCV

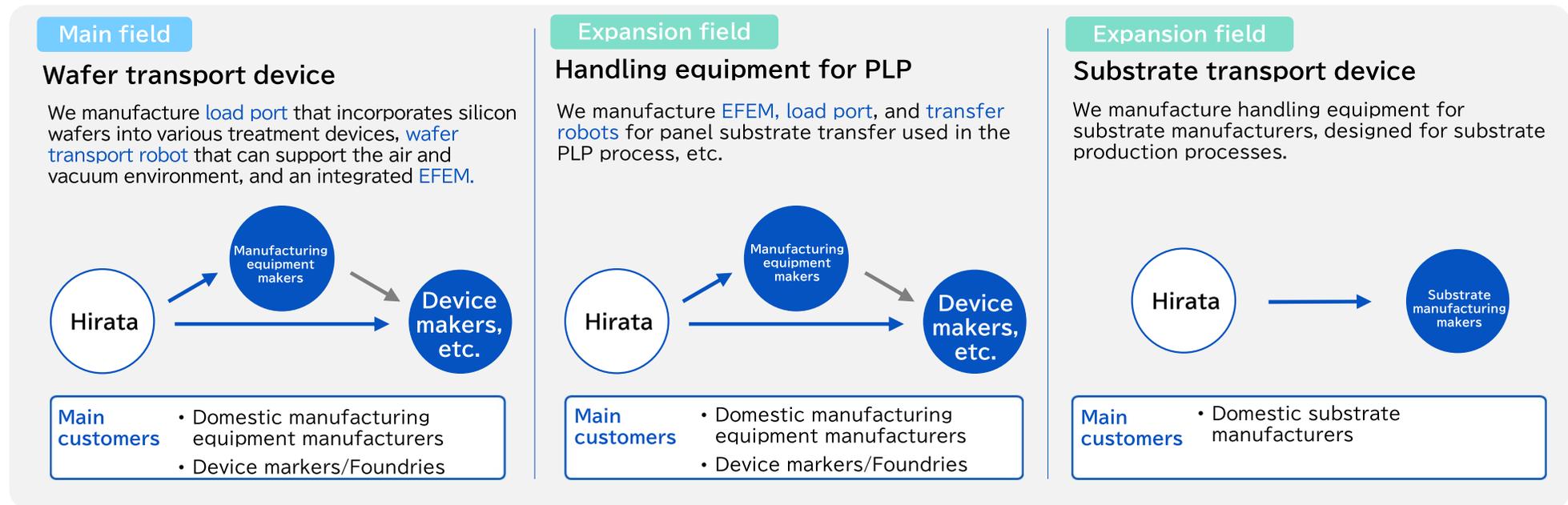
Hirata

Responding to the transformation of the automotive market and changes in customer strategies

Business Overview : Main Products of Semiconductor-related Business

- We manufacture and supply wafer and panel handling systems to equipment manufacturers and device manufacturers.

Main/Expansion Fields of Semiconductor-related business



Hirata's competitive advantages

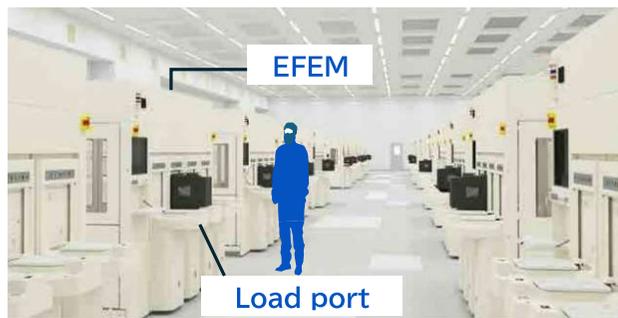
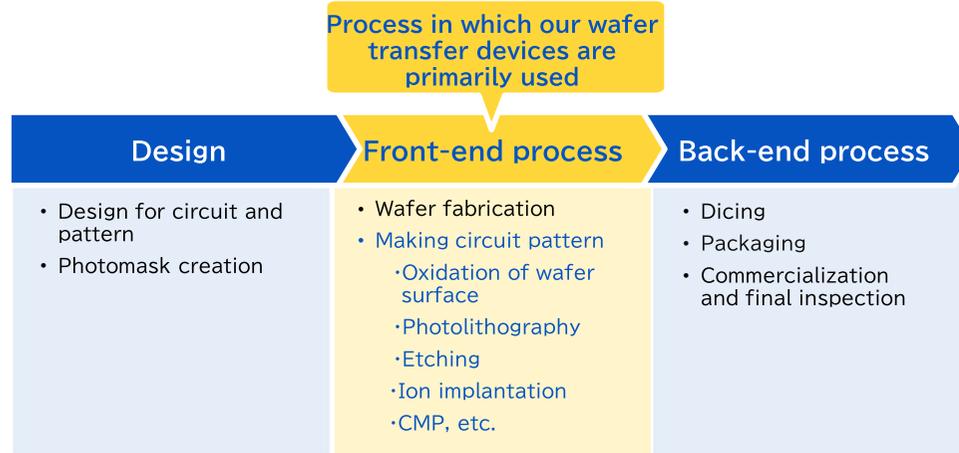
- A wealth of component lineup
- Knowledge technology required for customization and optimization to meet customer requirements
- Engineering ability to respond to customer requests from development to production and maintenance



Business Overview : Wafer Transport Device

- We design and manufacture **load ports** that take wafers into various processing equipment mainly used in the front-end process of semiconductor manufacturing, **wafer transfer robots** that transfer wafers, and **EFEMs** that integrate them.

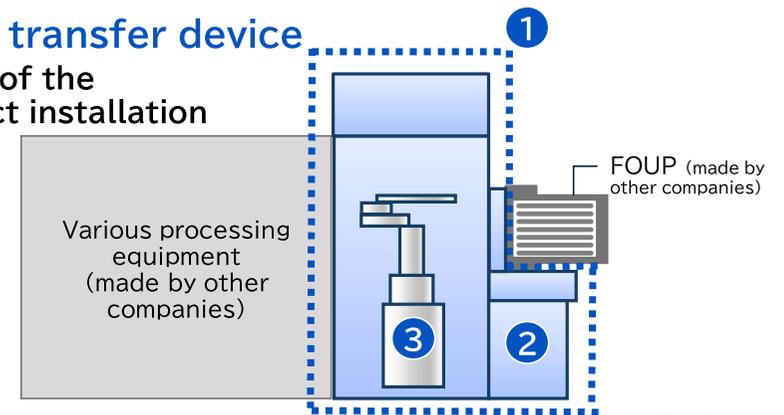
Semiconductor manufacturing process



- An EFEM and load ports are installed for each processing tool.
- A single production line uses multiple EFEMs and load ports.

Wafer transfer device

Image of the product installation



- 1 EFEM (Equipment Front End Module)**
 It is placed for each processing unit, with a wafer transfer robot inside and a load port on the front.
- 2 Load port**
 It opens and closes the lid on the back side of the FOUP*, a device that makes up the EFEM, but is also sold as a stand-alone item.
- 3 Wafer transport robot**
 Wafers are removed from the FOUP and transferred to the processing equipment. After processing, the wafers are stocked back in the FOUP. It is a device that makes up the EFEM, but is also sold as a stand-alone item.

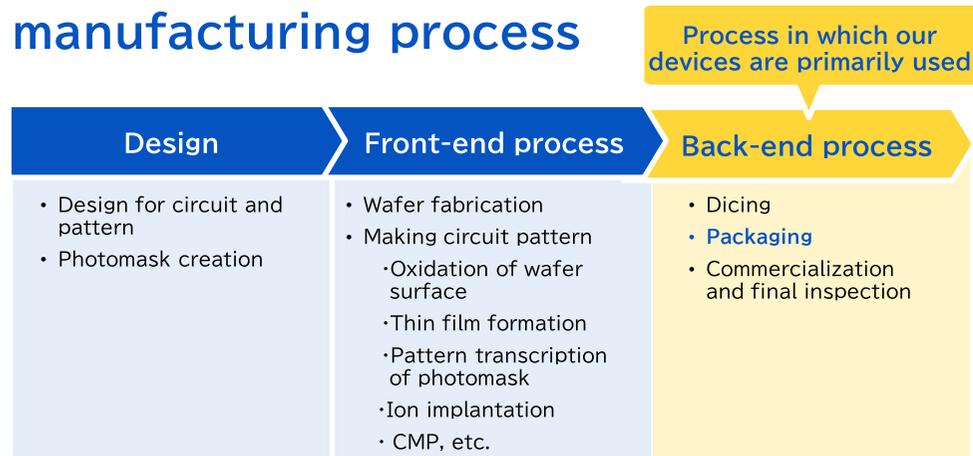


*FOUP : It is a container for wafers that holds multiple wafers and moves them between processes.

Business Overview : PLP

- We design and manufacture conveyance equipment used in PLP, an advanced packaging technology that is expected to expand.

Semiconductor manufacturing process



What is PLP (Panel Level Packaging) about?

- The packaging process involves rearranging numerous chips that have been individually cut after circuit formation onto thin, square-shaped substrates and then collectively molding them. This is a packaging technology called “PLP”.
- In PLP, panel substrates larger than the standard 300mm wafer size are commonly used.
- The panel substrate uses printed circuit boards, glass substrates for LCD panel manufacturing, and copper plates.

Difference of packaging process

Conventional packaging	Circuits are formed on wafers, and after cutting the chips into smaller pieces, they are individually bonded and encapsulated onto substrates to complete the product.
WLP (Wafer Level Package)	After cutting the chips individually, only the good chips are rearranged on the wafer , and then they are bonded and encapsulated onto the substrate while the chips are still on the wafer. They are then cut individually.
PLP (Panel Level Package)	After cutting the chips individually, only the good chips are rearranged on a square-shaped panel , and then they are bonded and encapsulated onto the substrate while the chips are still on the panel. They are then cut individually.

The chips that have been rearranged.



Business Overview : Other Automatic Labor-saving Equipment

- We manufacture products for various industrial fields such as organic EL vapor equipment, medical·physics and chemical equipment and so on.

Main/New Fields of Other Automatic Labor-saving Equipment

<p>Main field</p> <p>Organic EL Vapor Equipment</p> <p>We are contracted to manufacture vacuum evaporation equipment for OLED panels.</p> <p>Main customers Domestic device manufacturers</p>	<p>Main field</p> <p>Medical physiology and chemical equipment</p> <p>We manufacture a system for sample tests (pathological tissue specimen device and fully automatic continuous thinning device).</p> <p>Main customers Domestic medical specialty manufacturers</p>	<p>In addition, we propose and manufacture equipment and devices that address automation and labor-saving needs across a variety of industrial sectors.</p>
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Hirata's competitive advantages

- Extensive knowledge and expertise in production facilities and equipment in various fields
- An integrated framework covering development, production, and maintenance
- Engineering ability to respond to customer requests

<p>New field for monetization</p> <p>Focused ultrasound therapy equipment</p>	<ul style="list-style-type: none"> • We are jointly developing a focused ultrasound treatment device targeting pancreatic cancer with SONIRE Therapeutics Inc (Headquartered in Tokyo, hereinafter referred to as SONIRE). • We aim for non-invasive cancer treatment that fuses SONIRE's Ultrasonic Technology with our robot technology. • Clinical trials in humans have started, and we have begun development of the next generation of mass production equipment.
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Cautionary Statement with This Document

Please be aware that the performance forecasts and future predictions mentioned in this document are based on the information available to us at the time of its creation. They are subject to potential risks and uncertainties, such as changes in economic conditions, competition with other companies, and exchange rates. Therefore, please note that actual performance may significantly differ from the future outlook mentioned or described in this document due to various factors, including changes in the business environment.